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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No.
Akihisa HONGO et al. : Docket No. 2001_0133A
Serial No. 09/762,582 : Group Art Unit 1741
Filed April 12, 2001 : Examiner Brian Mutschler

SUBSTRATE PLATING
METHOD AND APPARATUS

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Sir:

In response to the Office Action of May 7, 2003, the period for response to which having been extended by three months to November 7, 2003, please amend the above-identified U.S. Patent Application as follows: